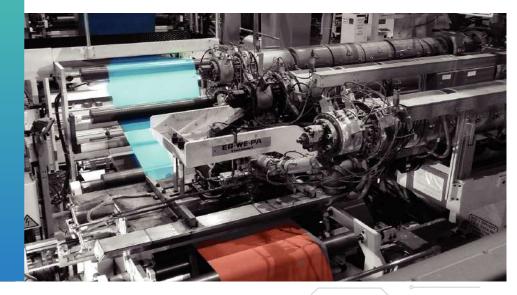


DATASHEET

Blue-PX

BPX245-120-H/H BPX245-60-H/H BPX245-30-H/H BPX245-20-H/H BPX245-16-H/H



PCB Laminate for RF&MW Applications

BluePX is based on PureBlue proprietary polymer chemistry, modification methods and continuous lamination technology.

Both the process, the substrate structure and the composition are protected by existing patents and patent pendings.



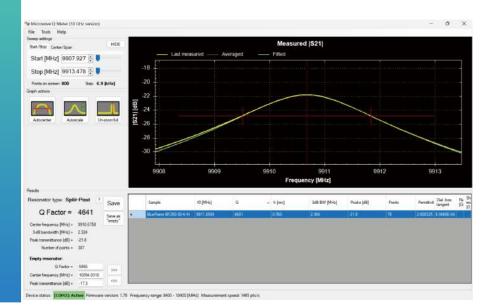


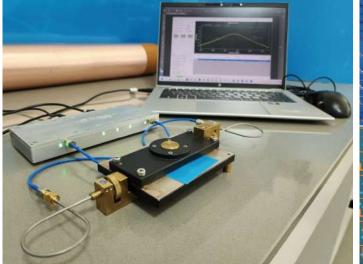
DATASHEET

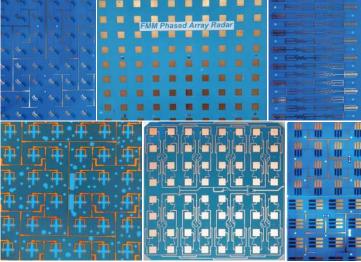
Blue-PX

BPX245-120-H/H BPX245-60-H/H BPX245-30-H/H BPX245-20-H/H BPX245-16-H/H

PCB Laminate for RF&MW Applications







The Blue-PX laminate is designated to meet manual and robotic soldering assembly processing.

The absolute glass fiber free system delivers unique nearly uniform (X-Y-Z) CTE below 100 ppm/°C.

Multiple short time expositions to heat of 150 °C, capacity to continuously operate at above 120 °C.

The proprietary to PureBlue continuous lamination process of high throughput secures tight thickness tolerance and very narrow uctuation of dielectric constant.

The BPX245 polymer compound features highly cross-linked polyolefin system designated to provide the lowest insertion loss in the most demanding and sensitive RF and MW applications when the lowest possible loss factor is demanded.

Superior balance of mechanical and electrical performance make the BPX245 laminate system the material of choice for your lowest loss high frequency applications.

The isotropic subtrate structure secures substantial advantage in PIM readings vs. anisotropic analogies.

The highest impact was recorded with dense PTH designs, better than -163 dBc under dynamic test and better than -170 dBc under static one.

PIM designated lowest profile foils apply in our performance-on-demand product versions.

Lowest-loss PCB Laminates





Typical Specification Values

Property	IPC-TM 650 or ASTM	Units	Value	Condition / Remarks	
Dielectric Constant	IPC 2.5.5.5		2.45±0.02	@10 GHz 23 °C	
Dissipation Factor			0.00046	@10 GH2 23 C	
Peel Strength	IPC 2.4.8	N/mm	1.8-2.1	Typical	
Moisture Absorption	IPC 2.6.2.1	wt. %	<0.06	Typical	
Volume Resistivity	IPC 2.5.17.1	MΩ - cm	>3X10 ⁷		
Surface Resistivity	IPC 2.5.17.1	MΩ - cm	>3X10 ⁷		
Dielectric Strength	IPC 2.5.6	kV/mm	19.7		
Flexural Strength, min	IPC 2.4.4	GPa	4		
Thermal Conductivity	ASTM C518	W/m-K	0.22		
x-y-z CTE, (-45 to 140°C)	DMA/TMA	Ppm/°C	<100		
Flammability	UL-94		НВ		
Recommended operational temperature range		°C	-45 to +125	For operation outside this temperature range please ask your technical contact.	
After Etch Substrate Contraction, max.	Recommended compensation	0/	0.25 MD		
		%	0.20 TD		
RoHS and Lead Free compatibility			Compatible		



Electro Deposited HTE Copper Foil Specifications

Typical copper cladding is 15 μ HTE specified below. Other foil thickness - 12, 18, 24 and 35 may apply per demand. Other foil types may apply - reverse treated, rolled. Copper foil may be replaced with aluminum rolled. Aluminum thickness - 20 to 50 μ

Nominal	Area	Tensile strength,	Elongation, %	Resistivity at 20 °C,
thickness, μm	weight, g/m2	N/mm2		Ohm g/m2
15± 1	125 ± 10	> 245	> 3	< 0,162

Facture	Unit	Gauge	IPC	
Feature		25μ	IPC-4562	IPC-MF-650
Shiny side roughness, Ra	μ	0,2-0,4	3.5.6	2.2.17
Matt side roughness, Rz	μ	4-5	3.4.5	2.2.17
Tensile strength, room temperature	MPa,	> 276	3.5.1	2.4.18
Elongation, room temperature	%	> 10	3.5.3	2.4.18
Solderability	Meets requirements	of IPC-4562	3.6.3	2.4.12

Panel Thickness (excluding copper foil)

BPX245-120-H/H – 3048 μ / 0.120" with a tolerance of \pm 75 μ

BPX245-60-H/H - 1524 μ / 0.060" with a tolerance of \pm 40 μ

BPX245-30-H/H - 760 μ / 0.030" with a tolerance of \pm 20 μ

BPX245-20-H/H – 508 μ / 0.020" with a tolerance of ± 15 μ

BPX245-16-H/H – 406 μ / 0.016" with a tolerance of ± 12 μ

Panel Dimensions

- Standard 608X1220 mm
- Panel length may be increased upon arrangement to maximize the yield for massive orders upon arrangement.

Lowest-loss PCB Laminates

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